

## CLAIMS

### What is claimed is:

1. A plate evaporator, comprising:
  - a first thermal conductive element having a first joining portion formed at rim thereof;
  - 5 and
  - a second thermal conductive element which is like a cap having a second joining portion formed at rim thereof and correspondent to said first joining portion, during assembling said first and said second thermal conductive elements, said first and said second joining portions are engaged.
- 10 2. A plate evaporator according to claim 1, wherein outer surface of said first thermal conductive element is formed with a plurality of heat-dissipation fins.
3. A plate evaporator according to claim 1, wherein said first thermal conductive element is a plate element.
- 15 4. A plate evaporator according to claim 1, wherein said first thermal conductive element is like a cap having said first joining portion formed on rim of said cap.
5. A plate evaporator according to claim 1, wherein said first thermal conductive element formed with first reinforced blocks in inner surface thereof, said second thermal conductive element formed with second reinforced blocks in inner surface thereof and corresponding to said first reinforced blocks, therefore, said first and said second reinforced blocks corresponding to each other when said first and said second thermal conductive elements are joined.
- 20 6. A plate evaporator according to claim 1, wherein a working fluid is filled after said first and said second thermal conductive elements are jointed.
7. A plate evaporator according to claim 1, wherein said second thermal conductive

element is formed with capillary structure.